

Raise3D Pro3 HS Series

Beyond Speed: 3D Printing Large Composite Parts Made Simple

The Raise3D Pro3 HS Series is a powerful professional-grade 3D printer that builds upon the Pro3 Series with integrated Hyper FFF® technology. It features leading speeds for printing composite materials with high efficiency and reliability. The upgraded motion control system with a closed-loop stepper motor further improves the precision and accuracy of high-speed printing, making it ideal for printing demanding industrial applications with minimal manual intervention.



High Speed Printing with High-Performance Composite Materials

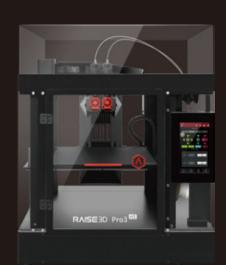




Longer-Lasting Reliability and Durability



Maximize Production Efficiency with Minimal Manual Intervention





- Built-in Hyper FFF[®] Technology
- New Printing Build Plate
- 2.5kg Large Roll Storage Boxes*
 *2.5kg filament box needs to be purchased separately

- Motion Control Upgrade with a Closed-Loop Motor
- New RFID Filament Sensor
- Auto Filament Switching

Printer	Raise3D Pro3 HS		Raise3D Pro3 Plus HS		
Build Volume (W × D × H)	Single Extruder Print	Dual Extruder Print	Single Extruder Print	Dual Extruder Print	
	300 × 300 × 300 mm (11.8 × 11.8 × 11.8 inch)	255 × 300 × 300 mm (10 × 11.8 × 11.8 inch)	300 × 300 × 605 mm (11.8 × 11.8 × 23.8 inch)	255 × 300 × 605 mm (10 × 11.8 × 23.8 inch)	
Machine Size (W × D × H)	620 × 626 × 760 mm (24.4 × 24.6 × 29.9 inch)		620 × 626 × 1105 mm (24.4 × 24.6 × 43.5 inch)		
Weight -	Net Weight	Gross Weight (Carton with Pallet)	Net Weight	Gross Weight (Carton with Pallet)	
	54 kg (119 lbs)	75.7 kg (166.9 lbs)	64 kg (141 lbs)	88.7 kg (195.5 lbs)	
General	Print Techno Print Head Sys Filament Diam XYZ Step Standard Printing Sp Build F Build Plate Leve Heated Bed Mat Heated Bed Max Tempera Nozzle Diam Max Nozzle Tempera Layer He Automatic Filament Switch RFID Set Filament Run-Out Set Filament Run-Out Set Filament Run-Out Set Filament Run-Out Set Eve Smart Assis Connect Noise Emis Operating Amb	tem Dual-head with Electronic eter 1.75 mm Size 0.78125, 0.78125, 0.0781 300 mm/s Plate Flexible Steel Plate with E erial Silicone ture 120°C eter 0.4 mm (Default), 0.2/ 0.6 sture 320°C ight The Pro3 HS Series is con the layer height can vary To achieve stable print re a layer height between 0 hing Available (Coming Soon) Available (Coming Soon) asor Available (Coming Soon) Available HEPA Filter with Activated tant Available wi-Fi, LAN, USB port, Live sion < 55 dB (A) While Printing ient 15-30°C, 10-90% RH, non	Dual-head with Electronic Lifting System 1.75 mm 0.78125, 0.78125, 0.078125 micron 300 mm/s Flexible Steel Plate with BuildTak Mesh-leveling with Flatness Detection Silicone 120°C 0.4 mm (Default), 0.2/ 0.6/ 0.8/ 1.0 mm (Available) 320°C The Pro3 HS Series is compatible with 0.2, 0.4, 0.6, 0.8 and 1.0 mm nozzles, and the layer height can vary between 0.05-0.6 mm. To achieve stable print results, when using 0.4 mm nozzles, we recommend using a layer height between 0.1-0.3 mm. Available (Coming Soon) Available (Coming Soon) Available HEPA Filter with Activated Charcoal Available Wi-Fi, LAN, USB port, Live Camera < 55 dB (A) While Printing 15-30°C, 10-90% RH, non-condensing		
Electrical	Power Supply Ir Power Supply Ou		100-240 V AC, 50/ 60 Hz 230 V @ 3.3 A 24 V DC, 600 W		
Material	Material T Third Party Mat	Hyper Speed: PLA/ ABS Industrial: PPA CF/ PPA G Premium: PLA/ ABS/ ASA	Hyper Core: PPA CF/ PPA GF/ ABS CF Hyper Speed: PLA/ ABS Industrial: PPA CF/ PPA GF/ PET CF/ PET GF/ PETG ESD/ PET Support/ PPA Support Premium: PLA/ ABS/ ASA/ PETG/ PC/ TPU-95A/ PVA+ Supported by Raise3D OFP (Open Filament Program)*		
Software	Slicing Softv Supported File Ty Supported Machine Code T	vpes STL/ OBJ/ 3MF/ OLTP/ STI OS Windows/ macOS/ Linux	STL/ OBJ/ 3MF/ OLTP/ STEP/ STP/ IGES/ IGS Windows/ macOS/ Linux		
Printer Controller	User Inter Netv Power Loss Reco Screen Resolu Motion Contro Logic Contro Men Onboard F	vork Wi-Fi, Ethernet very Available tion 1024 × 600 oller Atmel ARM Cortex-M4 12 oller NXP ARM Cortex-A9 Quar nory 1 GB	Wi-Fi, Ethernet Available 1024 × 600 Atmel ARM Cortex-M4 120 MHz FPU NXP ARM Cortex-A9 Quad 1 GHz 1 GB 16 GB Embedded Linux		

*For detailed information and slicing profiles of the materials supported by Raise3D OFP, please visit https://www.ideamaker.io/.



Authorized Distributor

